

600V, 30A, Trench FS II Fast IGBT

General Description:

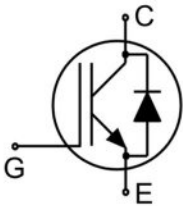
Using MJ's proprietary trench design and advanced FS (Field Stop) second generation technology, the 600V Trench FSII IGBT offers superior conduction and switching performances, and easy parallel operation;

Features

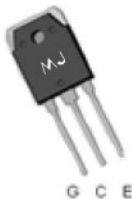
- ◆ Trench FSII Technology offering
- ◆ Very low $V_{CE(sat)}$
- ◆ High speed switching
- ◆ Positive temperature coefficient in $V_{CE(sat)}$
- ◆ Very tight parameter distribution
- ◆ High ruggedness, temperature stable behavior

Application

- ◆ Air Condition
- ◆ Inverters
- ◆ Motor drives



Schematic diagram



TO-3P

Package Marking and Ordering Information

Device	Device Package	Device Marking
MJ30TD60BP	TO-3P	MJ30TD60BP

Absolute Maximum Ratings ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Units
Collector-Emitter Voltage	V_{CES}	600	V
Gate- Emitter Voltage	V_{GES}	± 30	V
Collector Current	I_C	60	A
Collector Current @ $T_c = 100^{\circ}\text{C}$	I_C	30	A
Pulsed Collector Current, t_p limited by T_{jmax}	I_{Cplus}	90	A
turn off safe operating area, $V_{CE}=600\text{V}$, $T_j=150^{\circ}\text{C}$	-	90	A
Diode Continuous Forward Current @ $T_c = 100^{\circ}\text{C}$	I_F	30	A
Diode Maximum Forward Current	I_{FM}	90	A
Power Dissipation @ $T_c = 25^{\circ}\text{C}$	P_D	190	W
Power Dissipation @ $T_c = 100^{\circ}\text{C}$	P_D	95	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	$^{\circ}\text{C}$
Maximum Temperature for Soldering	T_L	260	$^{\circ}\text{C}$
Short circuit withstand time $V_{GE}=15.0\text{V}$, $V_{CC}\leq 400\text{V}$, Allowed number of short circuits<1000Time between short circuits: $\geq 1.0\text{s}$, $T_j\leq 150^{\circ}\text{C}$	t_{sc}	5	us

Thermal Characteristic

Parameter	Symbol	Value	Units
Thermal Resistance, Junction to case for IGBT	$R_{\theta JC}$	0.78	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to case for Diode	$R_{\theta JC}$	1.08	$^{\circ}\text{C/W}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	40	$^{\circ}\text{C/W}$

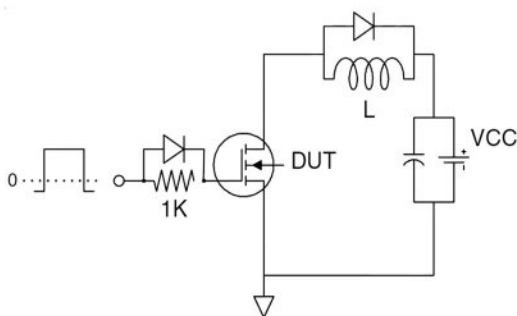
Electrical Characteristics (T_c=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions		Value			Units
				Min	Typ	Max	
Static Characteristics							
Collector-Emitter Breakdown Voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_{CE}=1mA$		600	-	-	V
Collector-Emitter Leakage Current	I_{CES}	$V_{GE}=0V, V_{CE}=600V$		-	-	4	uA
Gate to Emitter Forward Leakage	$I_{GES(F)}$	$V_{GE}=+30V, V_{CE}=0V$		-	-	200	nA
Gate to Source Reverse Leakage	$I_{GES(R)}$	$V_{GE}=-30V, V_{CE}=0V$		-	-	200	nA
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=30A$ $V_{GE}=15V$	$T_J=25^{\circ}C$	-	1.7	1.9	V
			$T_J=150^{\circ}C$	-	1.9	-	V
Gate Threshold Voltage	$V_{GE(th)}$	$I_C=1mA, V_{CE}=V_{GE}$		4.0	5.0	6.0	V
Dynamic Characteristics							
Input Capacitance	C_{ies}	$V_{CE}=25V, V_{GE}=0V,$ $f=1MHz$		-	3552	-	pF
Output Capacitance	C_{oss}			-	106	-	pF
Reverse Transfer Capacitance	C_{rss}			-	67	-	pF
Gate Charge	Q_{Gate}	$V_{CC}=480V, I_C=30A$ $V_{GE}=15V$		-	132	-	nC
Gate to Emitter Charge	Q_{ge}			-	28	-	nC
Gate to Collector Charge	Q_{gc}			-	54	-	nC
Short circuit collector current Max.1000 short circuits Time between short circuits: $\geq 1.0s$	$I_{C(SC)}$	$V_{GE}=15V, V_{CC}\leq 400V,$ $t_{sc}\leq 5\mu s, T_J\leq 150^{\circ}C$		-	190	-	A
Switching Characteristics							
Turn-on Delay Time	$t_{d(ON)}$	$V_{CC}=400V, I_C=30A$ $V_{GE}=0/15V, R_g=5\Omega$ Inductive Load		-	19	-	ns
Rise Time	t_r			-	17	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	166	-	ns
Fall Time	t_f			-	16	-	ns
Turn-On Switching Loss	E_{on}			-	0.36	-	mJ
Turn-Off Switching Loss	E_{off}			-	0.32	-	mJ
Total Switching Loss	E_{is}			-	0.68	-	mJ

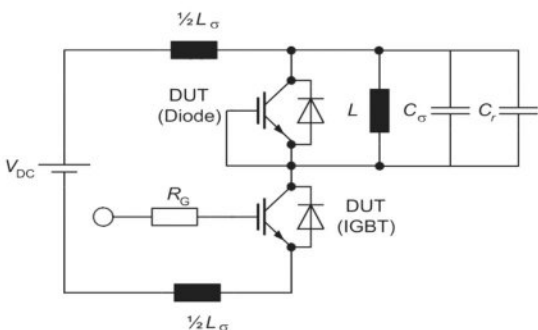
Electrical Characteristics of the Diode (Tc= 25°C unless otherwise specified):

Parameter	Symbol	Test Conditions	Rating			Units
			Min	Typ	Max	
Diode Forward Voltage	V _{FM}	I _F =30A	-	1.7	1.9	V
Reverse Recovery Time	T _{rr}	I _F =30A, di/dt=200A/uS	-	178	-	ns
Diode Peak Reverse Recovery Current	I _{RRM}		-	4	-	A
Reverse Recovery Charge	Q _{rr}		-	0.4	-	uC
Pulse width ttp≤380μs,δ≤2%						

Test Circuit

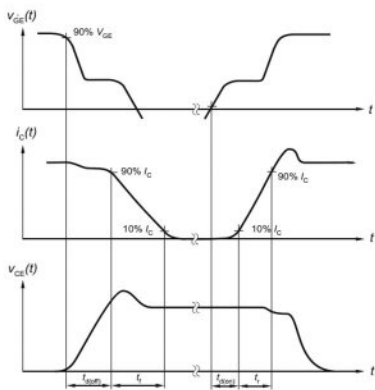


Gate Charge Test Circuit

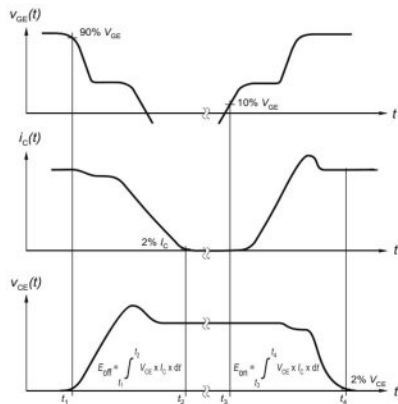


Switch Time Test Circuit

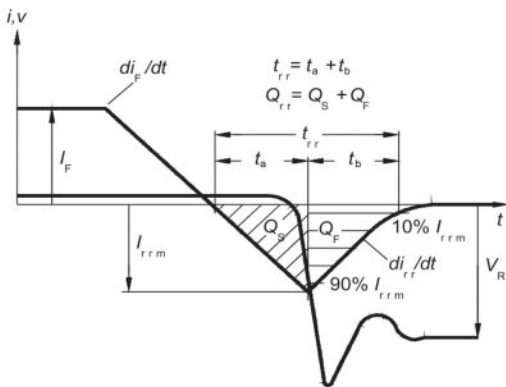
Switching characteristics



definition of switching times

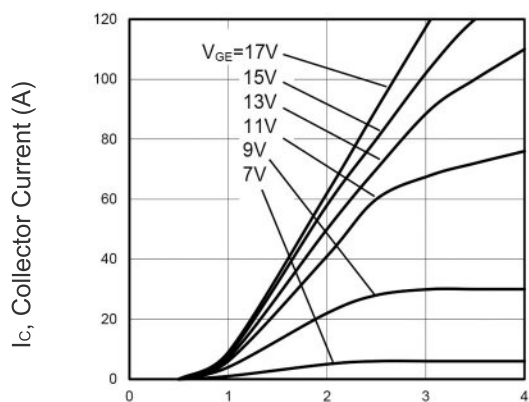


definition of switching losses



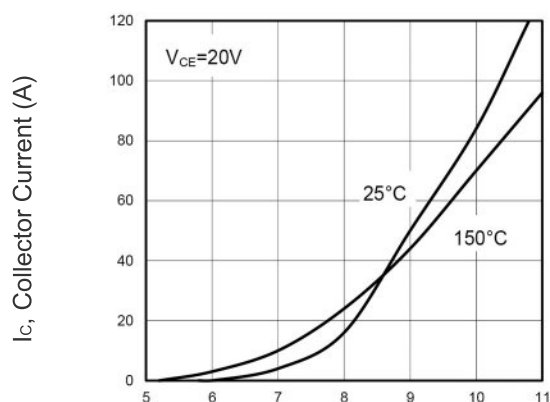
Definition of diode switching characteristics

Typical Electrical and Thermal Characteristics



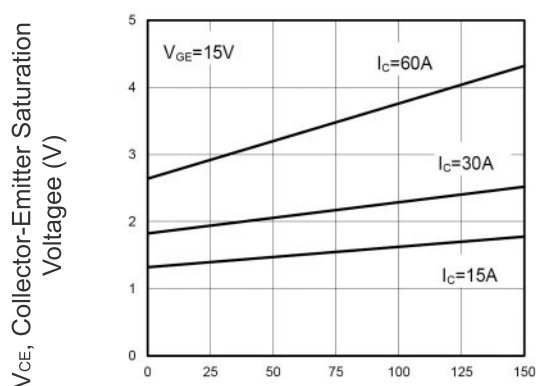
V_{CE} , Collector-Emitter Voltage (V)

Figure 1 Output Characteristics



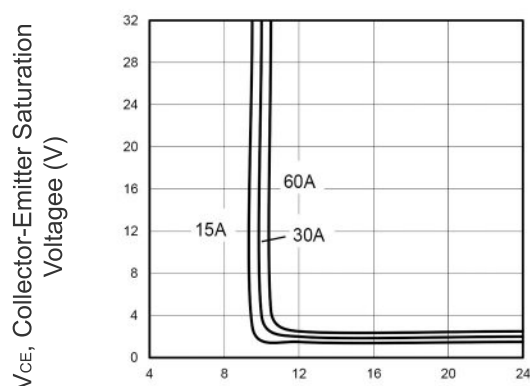
V_{GE} , Gate-Emitter Voltage (V)

Figure 2 Transfer Characteristics



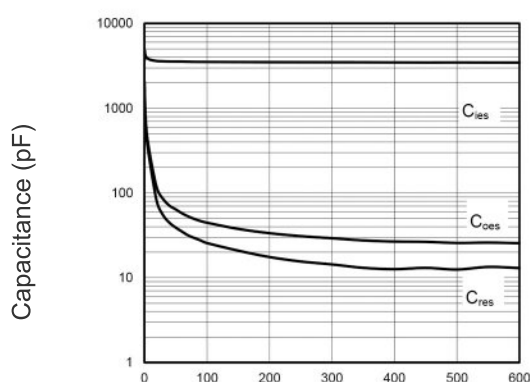
T_J , Junction Temperature ($^{\circ}C$)

Figure 3 V_{CEsat} vs. Case Temperature



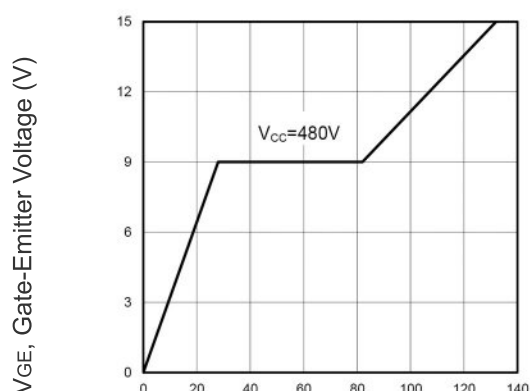
V_{GE} , Gate-Emitter Voltage (V)

Figure 4 Saturation Voltage vs. V_{GE}



V_{CE} , Collector-Emitter Voltage (V)

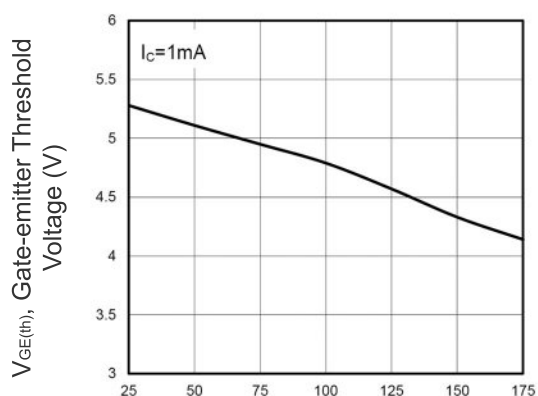
Figure 5 Capacitance Characteristics



Q_G , Total Gate Charge (nC)

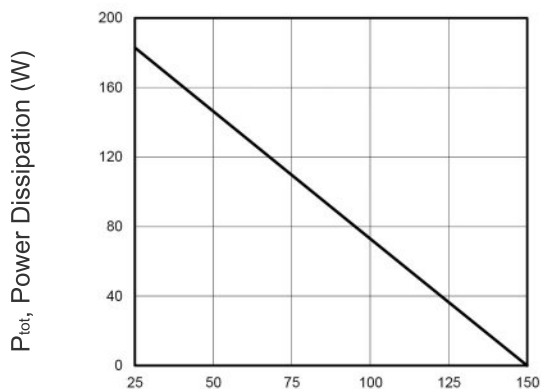
Figure 6 Gate charge waveform

Typical Electrical and Thermal Characteristics (continued)



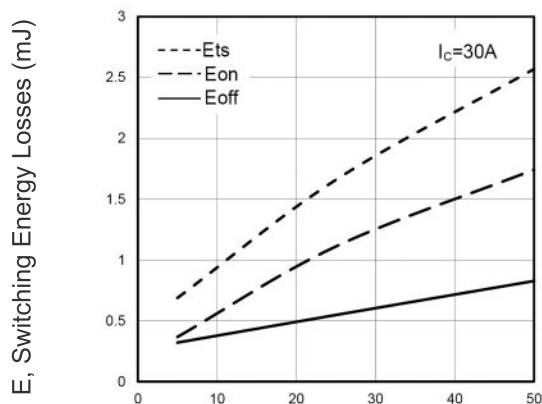
T_J, Junction Temperature (°C)

Figure 7 Gate-emitter Threshold Voltage as a Function of Junction Temperature



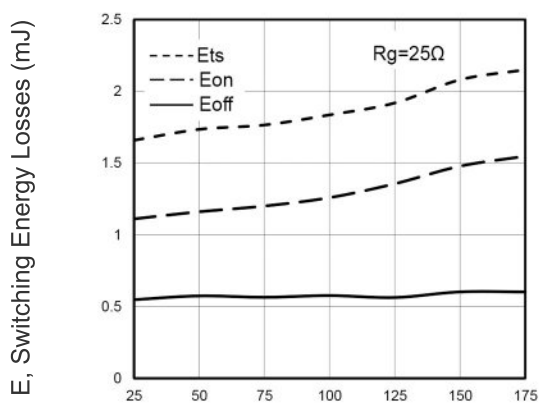
T_C, Case Temperature (°C)

Figure 8 Power Dissipation as a Function of Case Temperature



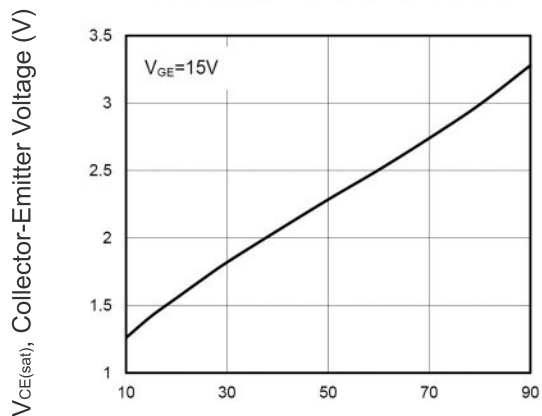
R_G, Gate Resistor (Ω)

Figure 9 Typical Switching Times as a Function of Gate Resistor



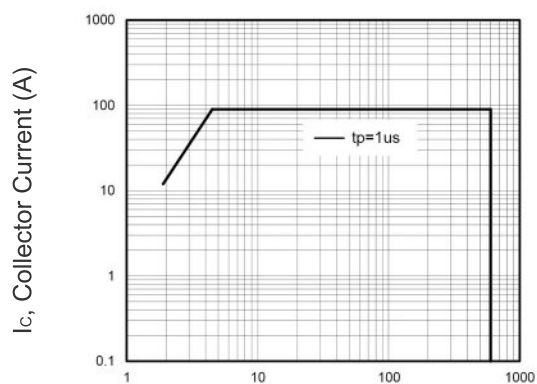
T_J, Junction Temperature (°C)

Figure 10 Typical Switching Times as a Function of Junction Temperature



I_C, Collector Current (A)

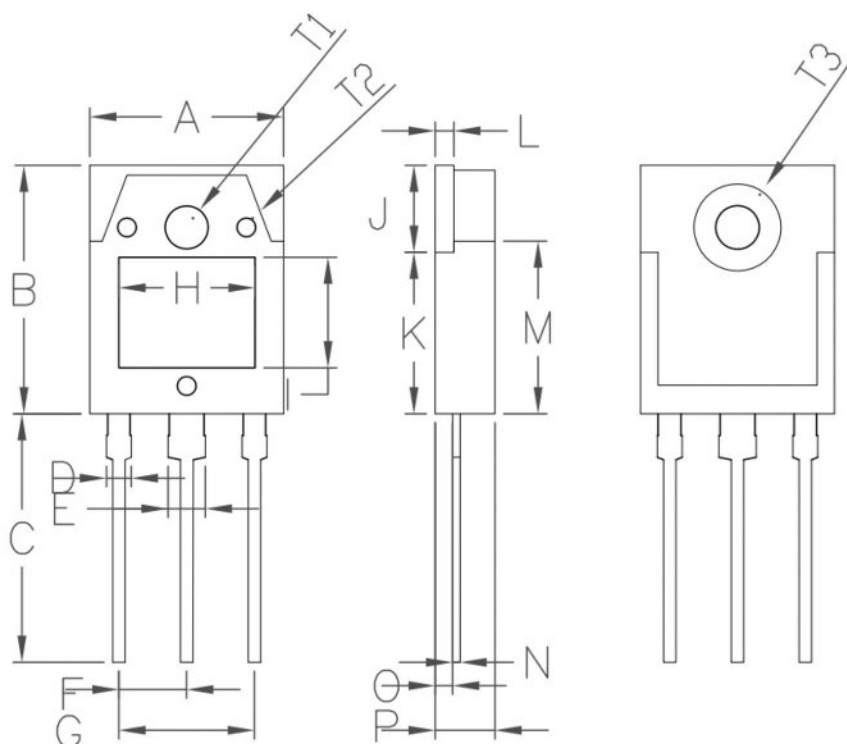
Figure 11 Typical Collector-emitter Saturation Voltage as a function of Collector Current



V_{CE}, Collector-Emitter Voltage (V)

Figure 12 Forward Bias Safe Operating Area

TO-3P-3L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	15.50	15.70	0.61	0.62
B	19.70	20.10	0.78	0.79
C	20.10	20.50	0.79	0.81
D	2.00		0.08	
E	3.00		0.12	
F	5.45		0.21	
G	10.90		0.43	
H	10.80	11.00	0.43	0.43
I	8.80	9.00	0.35	0.35
J	6.85	7.15	0.27	0.28
K	12.75	13.05	0.50	0.51
L	1.49	1.51	0.06	0.06
M	13.70	14.00	0.54	0.55
N	0.59	0.61	0.02	0.02
O	1.32	1.48	0.05	0.06
P	4.70	4.90	0.19	0.19
T1	3.50		0.14	
T2	1.50		0.06	
T3	7.00		0.28	

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